

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	4161413	(groove hole opening trench via)	US-PGPUB; USPAT; USOCR	OR	ON	2005/02/09 14:28
L2	572764	1 and (adhesive tape)	US-PGPUB; USPAT; USOCR	OR	ON	2005/02/09 14:01
L3	600289	1 and ((adhesive tape PSA) (pressure near3 sensitive))	US-PGPUB; USPAT; USOCR	OR	ON	2005/02/09 14:28
L4	215459	3 and (wafer chip die substrate)	US-PGPUB; USPAT; USOCR	OR	ON	2005/02/09 14:28
L5	126480	4 and (thin\$4 polish\$3 CMP)	US-PGPUB; USPAT; USOCR	OR	ON	2005/02/09 14:29
L6	118089	5 and (peel\$3 remov\$3 detach\$3 separat\$3)	US-PGPUB; USPAT; USOCR	OR	ON	2005/02/09 14:17
L7	2585	6 and PSA	US-PGPUB; USPAT; USOCR	OR	ON	2005/02/09 14:18
L8	1727	7 and (saw\$3 cut\$3 dic\$3)	US-PGPUB; USPAT; USOCR	OR	ON	2005/02/09 14:29
L9	21	8 and "438"/\$.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2005/02/09 14:21
L10	55	8 and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2005/02/09 14:22
L11	62	9 10	US-PGPUB; USPAT; USOCR	OR	ON	2005/02/09 14:22
L12	3848466	(groove hole opening trench via)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/09 14:28
L13	128182	12 and ((adhesive tape PSA) (pressure near3 sensitive))	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/09 14:28
L14	21313	13 and (wafer chip die substrate)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/09 14:28
L15	3026	14 and (thin\$4 polish\$3 CMP)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/09 14:29

L16	408	15 and (saw\$3 cut\$3 dic\$3)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/09 15:28
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